

POLYOLEFINIC RESIN COMPOSITION HIGHLY FILLED WITH INORGANIC MATERIAL

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Abstract

PURPOSE:Title composition usefu as a wire coating material, improved in tensile characteristics and fire retardance and the like, which comprises a polyolefinic resin and pulverized inorganic compounds containing a maleinized polymer, and if necessary, a variety of additives.

CONSTITUTION:Polyolefinic resin composition highly filled with inorganic material containing 1-50pts.wt. of (D) a maleinized polymer per 100pts.wt. of (B) pulverized inorganic componds, in the polyilefinic resin composition, comprising 100pts.wt. of (A) a polyolefinic resin and 50-300pts.wt. of (B) pulverized inorganic compounds and, if necessary, a variety of additives, where (A) is polyethylene, ethylele- vinyl acetate copolymer, or the like, (B) is Al(OH)3, zincborate, Mg(OH)2, or the like, the mean particle size of which is preferably 0.01-30mu, and (D) is a maleininized polybutadien or the like.

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